

## *Octagonal Relationship of Engineering Materials for Advanced Packaging*

New challenges are facing by engineering materials both in wafer and electronic package levels. The role of fundamental material science and engineering in resolving these challenges will be elaborated through the approach of “Octagonal Relationship of Engineering Materials”. Eight main facets (structure, process, performance, property, characterization, scale, sustainability, and value) governing the well-being of a designed material related to advanced electronic packaging will be briefly elaborated.

**Date: 13 April 2021 (Tuesday)**

**Time: 9.00-10.00 a.m. (M'sia Time, GMT +8:00)**

**Platform: CISCO WebEx**

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*\*E-certificates will be provided to all participant*



**SCAN ME**



**Prof. Ir. Dr. Cheong Kuan Yew**

Professor at the School of  
Materials and Mineral Resources  
Engineering, Universiti Sains  
Malaysia, Malaysia.

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